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To the Honorable Commission. 102216800	d the attached original documents or copy thereof.
1 Name of conveying party(ies):	2 Name and address of receiving party(ies):
Yi-Li Hsiao Chin-Hsin Peng Cheng-Shun Chan Jiann-Sheng Chang Chun-Hao Tseng Chien-Ling Huang	Taiwan Semiconductor Manufacturing Co. Ltd. No. 121 Park Avenue 3 Science-Based Industrial Park Hsin-Chu, Taiwan, R.O.C.
3 Nature of conveyance: ■ Assignment □ Merger	Additional name(s) & address(es) attached □ Yes No
☐ Security Agreement ☐ Change of Name	
Other: Execution Date: July 10, 2002	
4 Application number(s) or patent number(s):	
If this document is being filed together with a new applic	ation, the execution date of the application is:07-10-02
A. Patent Application No(s). 10, 234068	B. Patent No(s)
Additional number Name and address of party to whom correspondence	rs attached? ☐ Yes ☒ No 6 Total number of applications and patents involved:
concerning document should be mailed:	1
RANDY W. TUNG Tung & Associates 838 W. Long Lake Road Suite 120	7 Total fee (37 CFR 3.41) \$40.00
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Randy W. Tung Name of Person Signing Signature	Sept. 3, 2002
	Date
Registration No. 31,311	number of pages including cover sheet, attachments, and document : 3

Washington, D.C. 20231

ASSIGNMENT

WHEREAS, we, HISLAG-YF-EI, CHIN-HSIN PENG, CHENG-SHUN CHAN, JIANN-SHENG CHANG, CHUN-HAO TSENG and CHIEN-LING HUANG have invented certain improvements in

AUTOMATIC SENSING WAFER BLADE AND METHOD FOR USING for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

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PATENT REEL: 013260 FRAME: 0465 Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Yi-Li Hsiao HSIAN-YI LI	Chin-Hsin Peng Chin-Hsin Peng Chin-Hsin Peng
Cheng-Shun Chan CHENG-SHUN CHAN	Jiann-Sheng Chang JIANN-SHENG CHANG
Chun-Hao Tseng CHUN-HAO TSENG	Chien-Ling Huang

TUNG & ASSOCIATES 838 W. Long Lake Road Suite 120 Bloomfield Hills, Michigan 48302

RECORDED: 09/03/2002

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PATENT REEL: 013260 FRAME: 0466